

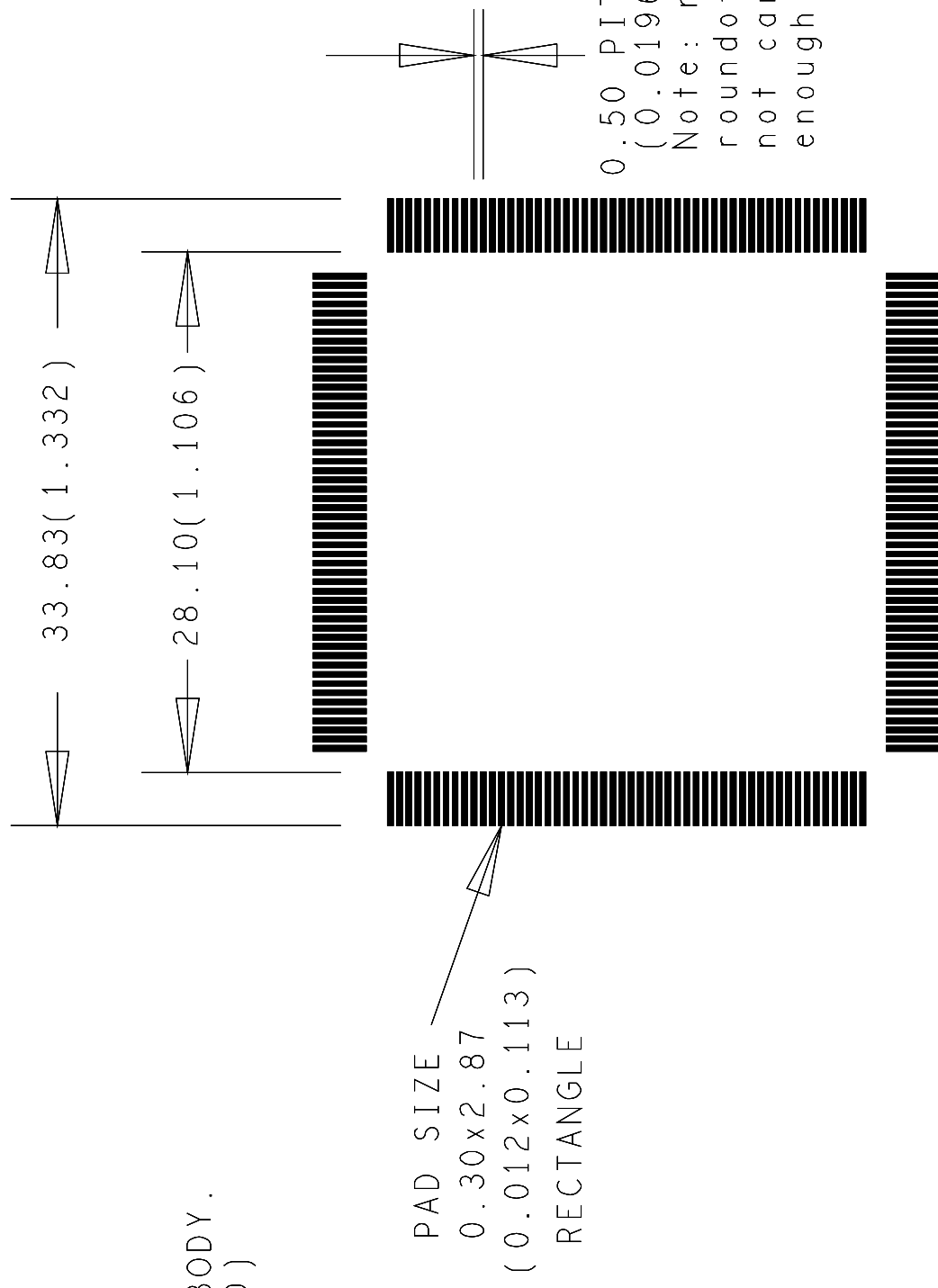
DIMENSIONS: mm( inches )

LEAD FORMING GUIDELINES:

APPLY THE FOLLOWING LEAD FORMING GUIDELINES TO ENSURE THE 208-LEAD CERAMIC QFP WILL FIT ONTO THIS FOOTPRINT.

- 1) FIRST LEAD BEND IS  $1.14 \pm .13$  (  $.045 \pm .005$  ) FROM THE BODY.
- 2) SECOND LEAD BEND IS MADE  $2.67 - 0 / + .51$  (  $.105 - 0 / + .020$  ) TO ALLOW PWB TO COMPONENT BODY CLEARANCE.
- 3) THE HEAL OF THE FOOT IS OFFSET FROM THE FIRST BEND BY  $0-.46$  (  $0-.018$  ).
- 4) THE FOOT OF THE LEAD IS  $1.14 \pm .13$  (  $.045 \pm .005$  ).

THESE LEAD FORMING GUIDELINES ARE COMPATABLE WITH IPC/EIA J-STD-001C FOR NOMINAL SOLDER FILLETS AND IPC-SM-782 FOR LAND PATTERN DESIGN.



RECOMMENDED FOOTPRINT FOR COMBINATION AEROFLEX  
208-CQFP FPGA/EMULATION TECHNOLOGY 208-PQFP SOCKET  
SOCKET PART NUMBER: S-QFP-SM-208-A